

1/4

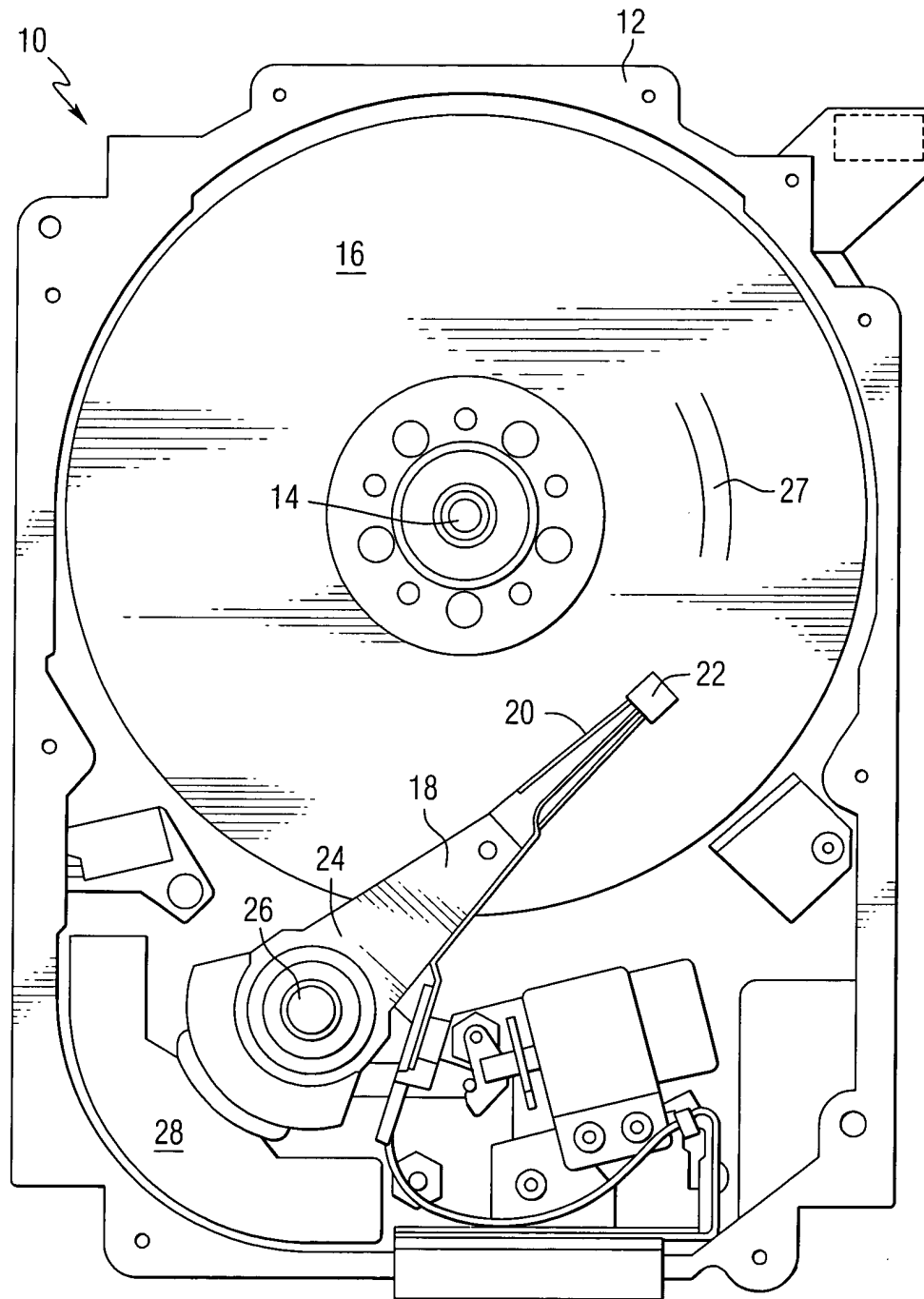


FIG. 1

A cross-sectional view of a semiconductor device 16. The device consists of a substrate 38, a middle layer 40, and a top layer 50. The top layer 50 is composed of four sub-layers: 52, 54, 42, and 44. A wavy arrow points to the top layer 50.

FIG. 3

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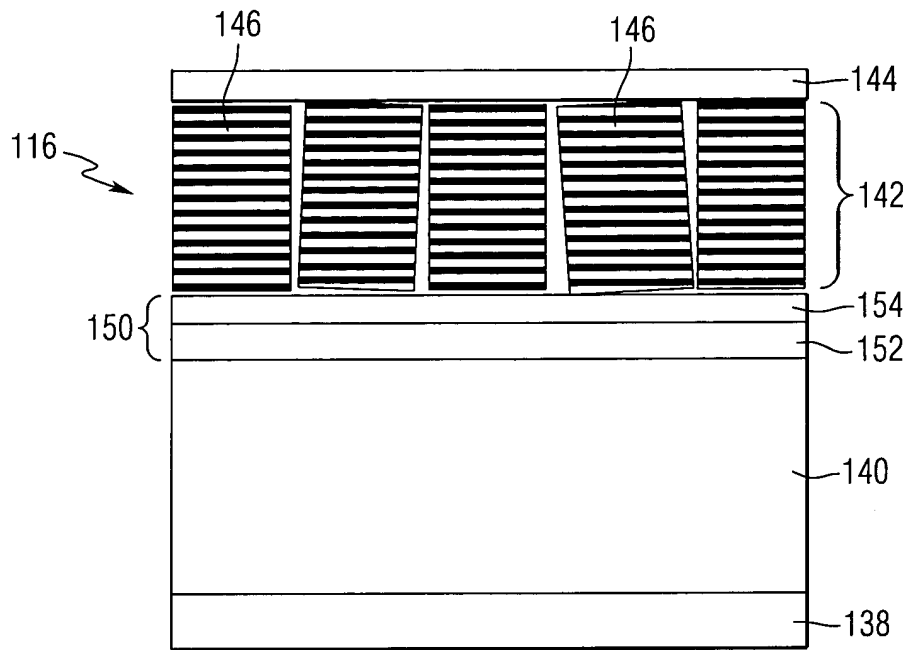


FIG. 4

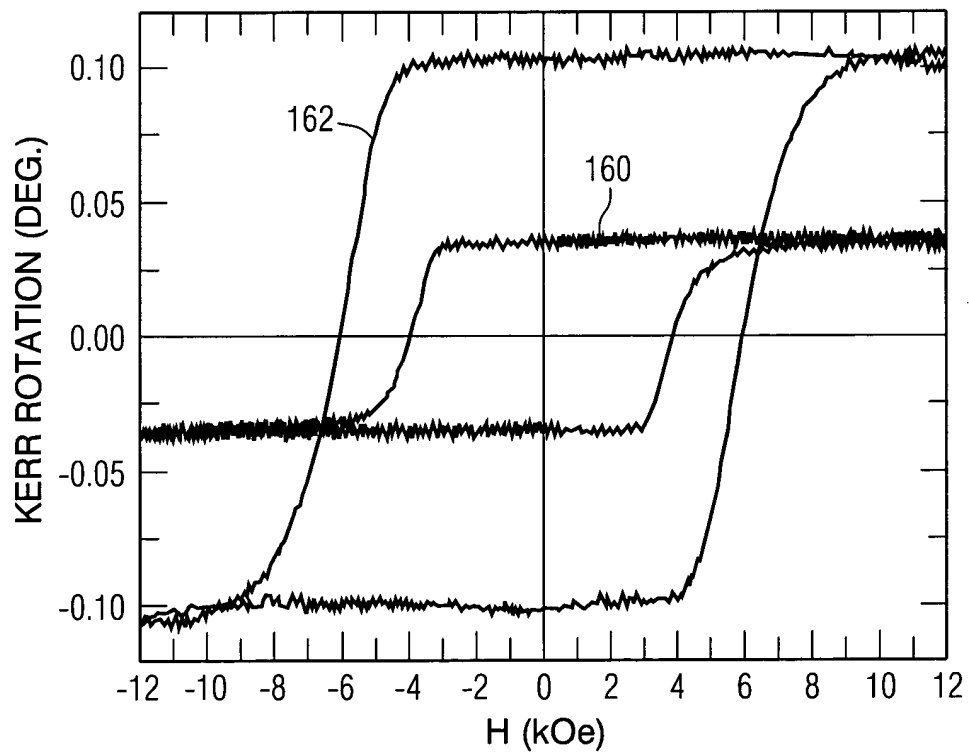


FIG. 5

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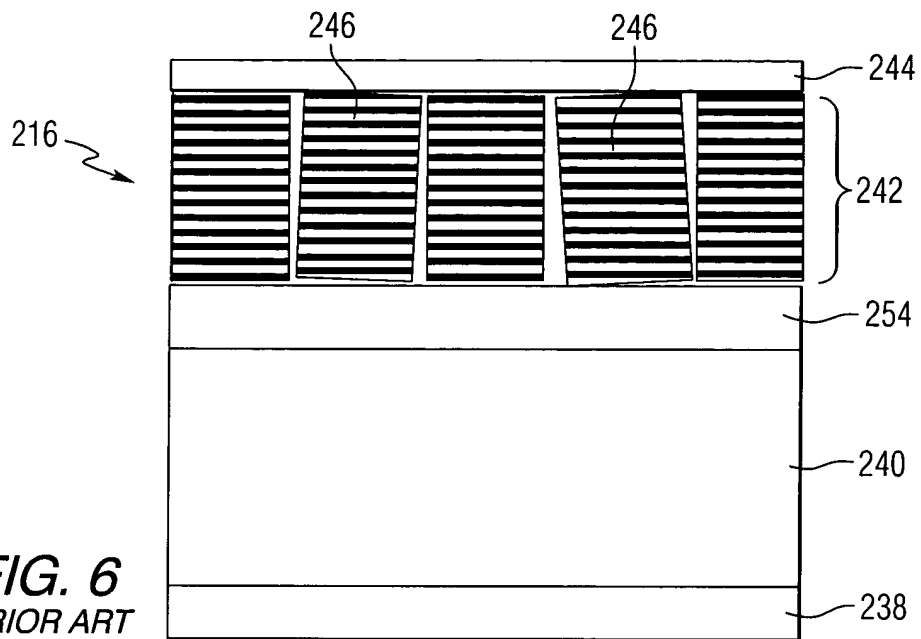


FIG. 6
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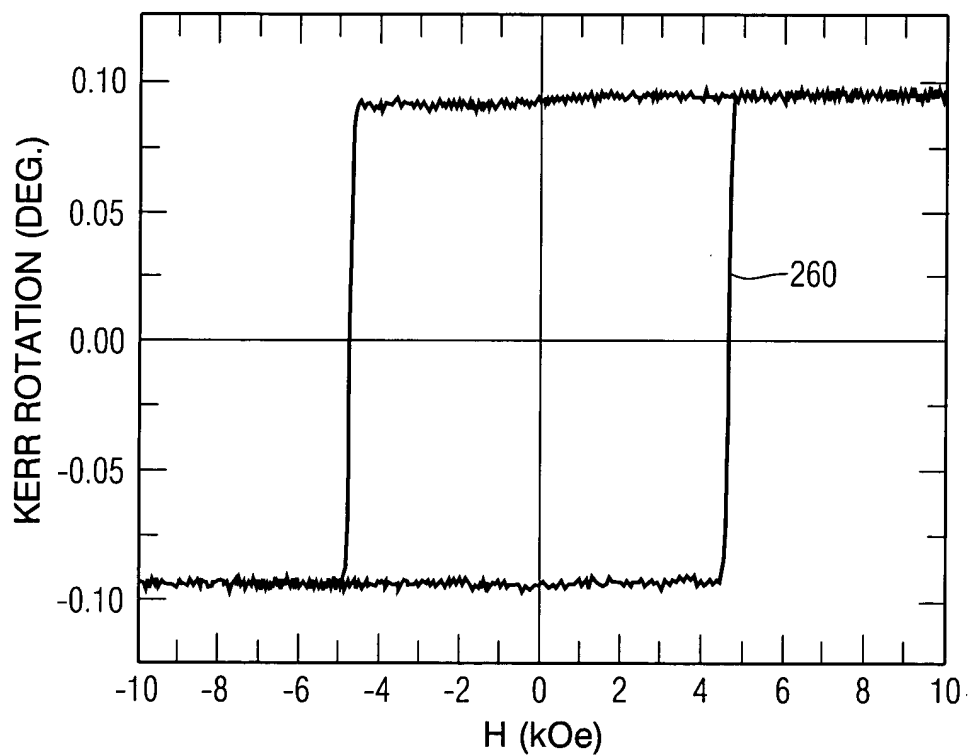


FIG. 7
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